12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260227000.2
Qualify TIEM as an additional Assembly/Test site for select devices
Change Notification / Sample Request

Date: February 27, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260227000.2
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LV4051ATPWRQ1	NULL
TLV9064QPWRQ1	NULL
SN74HCS05QPWRQ1	NULL
SN74HCS126QPWRQ1	NULL
SN74HCS32QPWRQ1	SN74HCS32QPWRQ1
SN74LV4053AQPWRQ1	SN74LV4053AQPWRQ1
SN74LV4052AQPWRQ1	NULL
SN74HCS595QPWRQ1	SN74HCS595QPWRQ1
TXU0304QPWRQ1	NULL
SN74HCS151QPWRQ1	NULL
SN74HCS14QPWRQ1	SN74HCS14QPWRQ1
TXU0104QPWRQ1	NULL
SN74LV4T125QPWRQ1	NULL
SN74LV4051AQPWRQ1	SN74LV4051AQPWRQ1
SN74HCS594QPWRQ1	NULL
SN74HCS03QPWRQ1	NULL
SN74HCS08QPWRQ1	SN74HCS08QPWRQ1
CD74HCT4066QPWRQ1	CD74HCT4066QPWRQ1
SN74HCS4075QPWRQ1	SN74HCS4075QPWRQ1
SN74HCS04QPWRQ1	SN74HCS04QPWRQ1
SN74HC21QPWRQ1	NULL
SN74HC08IPWRQ1	595-SN74HC08IPWRQ1
TLV7034QPWRQ1	NULL
TLV7044QPWRQ1	NULL
SN74HC132QPWRQ1	NULL
SN74HC14QPWRQ1	SN74HC14QPWRQ1
SN74AHCT125QPWRQ1	NULL
SN74HC165QPWRQ1	NULL
SN74HCS21QPWRQ1	NULL
SN74HCS74QPWRQ1	SN74HCS74QPWRQ1
SN74HCS365QPWRQ1	NULL
LSF0204QPWRQ1	LSF0204QPWRQ1
SN74HC08QPWRQ1	NULL
SN74HCS165QPWRQ1	NULL
CD74HC4051QPWRQ1	CD74HC4051QPWRQ1
OPA4991TQPWRQ1	NULL
SN74AHC08QPWRQ1	NULL
SN74HCS138QPWRQ1	NULL
SN74AC14QPWRQ1	NULL
SN74HC00QPWRQ1	NULL
LM339LVQPWRQ1	NULL
TLV9154QPWRQ1	NULL
SN74HCS125QPWRQ1	NULL
SN74HCS7002QPWRQ1	SN74HCS7002QPWRQ1
SN74HCS11QPWRQ1	SN74HCS11QPWRQ1
SN74HCS02QPWRQ1	SN74HCS02QPWRQ1
SN74HCS72QPWRQ1	SN74HCS72QPWRQ1
SN74HC74QPWRQ1	NULL
SN74HCS10QPWRQ1	SN74HCS10QPWRQ1

SN74HCS30QPWRQ1	NULL
SN74LV393ATPWRQ1	NULL
SN74AXC4T245QPWRQ1	NULL
SN74HCS20QPWRQ1	NULL
SN3257QPWRQ1	NULL
SN74HC138QPWRQ1	NULL
SN74HCS166QPWRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260227000.2	**PCN Date:**	February 27, 2026
Title:	Qualify TIEM as an additional Assembly/Test site for select devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	August 26, 2026	**Sample requests accepted until:**	April 28, 2026*

***Sample requests received after** April 28, 2026 **will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/ Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Melaka (TIEM) as an additional Assembly/Test site for the list of devices shown below. Material differences between sites are as follows.

	Current site	Additional Site
Assembly site	MLA	TIEM
Wire diam/type	0.96mil Au, 0.8mil Cu, 1mil Cu	0.8mil Cu, 1.0mil Cu
Mount compound	4147858	4211470
Mold compound	4211471	4228573
Lead finish	NiPdAu	Matte Sn
Marking difference*	TI logo, pin 1 dimple, with G4	TI letter, pin 1 dot, remove G4, mold cavity ID

* - Not all devices have TI logo/pin 1 dimple/G4 marking included in the symbolization, but for devices that do have, the proposed change applies.

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Review the SDP for full evaluation of the change based on the customer use case.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site Information:

Assembly Site	Assembly Site Origin	Assembly Country	Assembly City

	(22L)	Code (23L)	
TI Malaysia	MLA	MYS	Kuala Lumpur
TIEM	**CU6**	**MYS**	**Melaka**

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
G4
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

CD4051BQPWRQ1	SN74HC21QPWRQ1	SN74HCS27QPWRQ1
CD74HC125QPWRQ1	SN74HC21QPWRQ1-NG	SN74HCS30QPWRQ1
CD74HC4051QPWRQ1	SN74HC74QPWRQ1	SN74HCS32QPWRQ1
CD74HCT4066QPWRQ1	SN74HC86QPWRQ1	SN74HCS365QPWRQ1
INA4180A1QPWRQ1	SN74HCS00QPWRQ1	SN74HCS367QPWRQ1
INA4180A2QPWRQ1	SN74HCS02QPWRQ1	SN74HCS4075QPWRQ1
INA4180A3QPWRQ1	SN74HCS03QPWRQ1	SN74HCS594QPWRQ1
INA4180A4QPWRQ1	SN74HCS04QPWRQ1	SN74HCS595QPWRQ1
LM2902LVQPWRQ1	SN74HCS05QPWRQ1	SN74HCS596QPWRQ1
LM339LVQPWRQ1	SN74HCS08QPWRQ1	SN74HCS7002QPWRQ1
LMV324AQPWRQ1	SN74HCS09QPWRQ1	SN74HCS7266QPWRQ1
LSF0204QPWRQ1	SN74HCS10QPWRQ1	SN74HCS72QPWRQ1
OPA4991HQPWRQ1	SN74HCS11QPWRQ1	SN74HCS74QPWRQ1
OPA4991QPWRQ1	SN74HCS125QPWRQ1	SN74HCS86QPWRQ1
OPA4991RQPWRQ1	SN74HCS126QPWRQ1	SN74HCT165QPWRQ1
OPA4991TQPWRQ1	SN74HCS137QPWRQ1	SN74HCT595QPWRQ1
SN3257QPWRQ1	SN74HCS138QPWRQ1	SN74LV393ATPWRQ1
SN74AC14QPWRQ1	SN74HCS139QPWRQ1	SN74LV4051AQPWRQ1
SN74AHC08QPWRDL	SN74HCS14QPWRQ1	SN74LV4051ATPWRQ1
SN74AHC08QPWRQ1	SN74HCS151QPWRQ1	SN74LV4052AQPWRQ1
SN74AHC125QPWR	SN74HCS153QPWRQ1	SN74LV4053AQPWRQ1
SN74AHC32QPWRQ1	SN74HCS157QPWRQ1	SN74LV4T125QPWRQ1
SN74AHCT08QPWRQ1	SN74HCS164QPWRQ1	TL974QPWRQ1
SN74AHCT125QPWRQ1	SN74HCS16507QPWRQ1	TLV7034QPWRQ1
SN74AXC4T245QPWRQ1	SN74HCS165QPWRQ1	TLV7044QPWRQ1
SN74AXC4T774QPWRQ1	SN74HCS166QPWRQ1	TLV9004QPWRQ1
SN74HC00QPWRQ1	SN74HCS174QPWRQ1	TLV9024QPWRQ1
SN74HC02QPWRQ1	SN74HCS20QPWRQ1	TLV9034QPWRQ1
SN74HC08IPWRQ1	SN74HCS21QPWRQ1	TLV9064QPWRQ1
SN74HC08QPWRQ1	SN74HCS237QPWRQ1	TLV9154QPWRQ1
SN74HC132QPWRQ1	SN74HCS238QPWRQ1	TLV9354QPWRQ1
SN74HC138QPWRQ1	SN74HCS251QPWRQ1	TSV914AQPWRQ1
SN74HC139QPWRQ1	SN74HCS259QPWRQ1	TXU0104QPWRQ1
SN74HC14QPWRQ1	SN74HCS264QPWRQ1	TXU0204QPWRQ1
SN74HC165QPWRQ1	SN74HCS266QPWRQ1	TXU0304QPWRQ1

Qualification Report
Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)
Approve Date 12-February-2026

Product Attributes

Attributes	Qual Device: SN74AXC4T245QPWRQ1	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: LM5576QMH/NOPB	QBS Package Reference: LM5118Q1MH/NOPB	QBS Package Reference: DRV8876QPWPRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain,Interface	Signal Chain,Interface	Power Management	Logic	Signal Chain
Wafer Fab Supplier	RFAB	RFAB	RFAB	MAINEFAB	RFAB
Assembly Site	TIEMA	PHI	TIEMA	TIEMA	TIEMA
Package Group	TSSOP	SOT	TSSOP	TSSOP	TSSOP
Package Designator	PW	DYY	PWP	PWP	PWP
Pin Count	16	16	20	20	16

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74AXC4T245QPWRQ1 is qualified at MSL1 260C
Note 1: Affected devices in PCN have justification to use Package QBS references for Group A tests based on AEC-Q100 Rev-J Appendix 1 A1.3, assembly site and package attributes were qualified
Note 2: Affected devices in PCN have justification to use Process QBS references for Group B tests based on AEC-Q100 Rev-J Appendix 1 A1.2, silicon wafer fab and die attributes were qualified.

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: SN74AXC4T245QPWRQ1	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: LM5576QMH/NOPB	QBS Package Reference: LM5118Q1MH/NOPB	QBS Package Reference: DRV8876QPWPRQ1
Test Group A - Accelerated Environment Stress Tests												
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	Note 1	-	3/231/0	3/231/0	3/231/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	Note 1	-	3/231/0	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	Note 1	-	3/231/0	3/231/0	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	Note 1	-	3/231/0	3/231/0	3/231/0
TC-BP	A4.1.1	-	3	5	Post Temp Cycle Bond Pull	MIL-STD 883 Method 2011	Completed	Note 1		3/15/0	3/15/0	3/15/0
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	Note 1	-	3/36/0	3/36/0	3/36/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	Note 1	-	3/135/0	3/135/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	Note 1	-	-	-	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests												
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	Note 2	-	1/77/0	3/231/0	-
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	300 Hours	Note 2	3/231/0	-	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	Note 2	3/2400/0	-	-	-

Test Group C - Package Assembly Integrity Tests												
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	Note 1	1/15/0	1/30/0	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0	3/30/0	3/30/0	3/30/0	3/30/0
Test Group D - Die Fabrication Reliability Tests												
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests												
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	-	-	-	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2504-023

Automotive Qualification Summary
(As per AEC and JEDEC Guidelines)

Q006 TSSOP at TIEMA
Approve Date 13-February-2026

Product Attributes

Attributes	QBS Package Reference: LM5576QMH/NOPB	QBS Package Reference: LM5118Q1MH/NOPB	QBS Package Reference: DRV8876QPWPRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Logic	Signal Chain
Wafer Fab Supplier	RFAB	MAINEFAB	RFAB
Assembly Site	TIEMA	TIEMA	TIEMA
Package Group	TSSOP	TSSOP	TSSOP
Package Designator	PWP	PWP	PWP
Pin Count	20	20	16

This report represents AEC-Q006 7.1 Family Data Usage using technology driver and lead products that are most representative of the technology family

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Q006 Reference: LM5576QMH/NOPB	Q006 Reference: LM5118Q1MH/NOPB	Q006 Reference: DRV8876QPWPRQ1
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	3/231/0	3/231/0	3/231/0
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	3/66/0	3/66/0	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	3/66/0	3/66/0	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	-	-	-
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	-	-	-
HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	-	-	-
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	-	-	-
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	3/210/0	3/210/0	3/210/0
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST 2X	Review for delamination	Completed	3/66/0	3/66/0	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	3/9/0	3/9/0	3/9/0

TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	-	-	-
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	-	-	-
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	-	-	-
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	-	-	-
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	-	-	-
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	3/210/0	3/210/0	3/210/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	3/66/0	3/66/0	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	3/135/0	3/135/0	-
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	175C	500 Hours	-	-	3/135/0
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	-	-	-
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	3/132/0	3/132/0	-
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	175C	1000 Hours	-	-	3/132/0
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2504-023

ZVEI ID: SEM-PA-18, SEM-PA-11, SEM-PA-05, SEM-PA-08, SEM-PA-07, SEM-PA-13, SEM-TF-01

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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